

Product Specification

CUSTOMER: ERICSSON

DESCRIPTION: RF TRANSFORMER

MNC P/N: RFT-023SG

REVISION: X0

CUSTOMER P/N: REG7359910/4

ISSUED DATE: 2016-03-07

PHOTO OF
PRODUCT:

WEIGHT:

PREPARED BY	CHECKED BY	APPROVED BY
Sonny Zhang	Sonny Zhang	Simon Zhang

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CHANGE RECORD

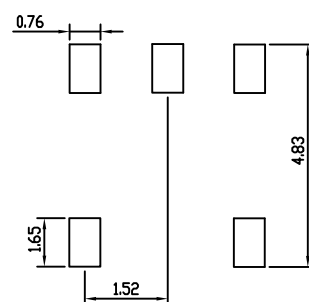
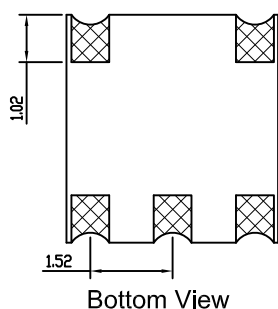
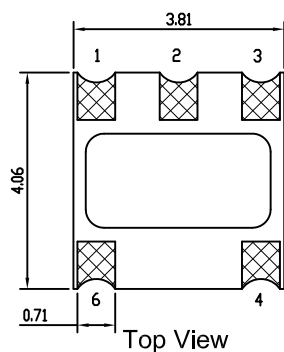
REV.	DESCRIPTION (Content or Reason For Change)	DATE	REVISER
X0	INITIAL RELEASE	2016-03-07	Sonny Zhang

- RF Transformer
- Impedance=50Ω
- Operating Temperature range: -40℃ to 85℃
- Storage Temperature range: -40℃ to 100℃
- RoHS Compliant

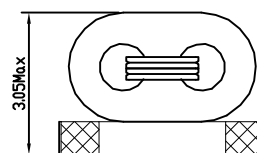
Electrical Specifications @25°C,Z ₀ =50Ω						
Part Number	Ω Ratio	Insertion Loss			DC Current	RF Power
	Pri:Sec(6-4:3-1)	0.2-500MHz	0.4-300MHz	1-100MHz		
RFT-023SG	1:2	3.0dB Max	2.0dB Max	1.0dB Max	250mA Max	0.25W Max
						0.2-500MHz

Note: Insertion Loss is referenced to mid-band loss 0.3dB typ. Measure back to back.

MECHANICAL DIMENSIONS



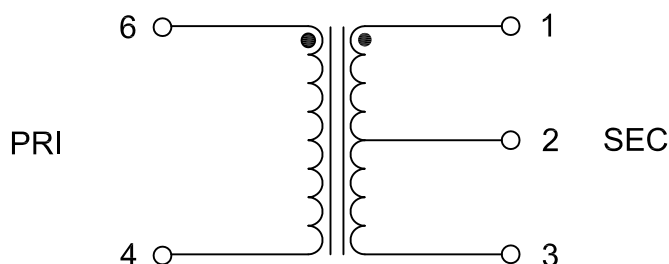
Recommended PAD Layout



Side View

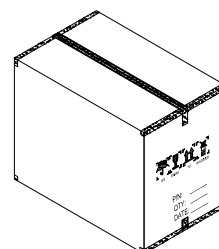
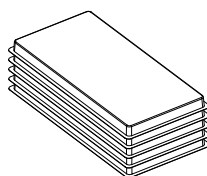
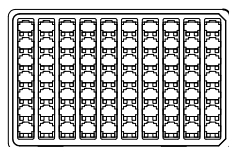
- Unless otherwise specified all tolerances are: ±0.25 in mm

SCHEMATICS



PACKING:

☐ Tray:

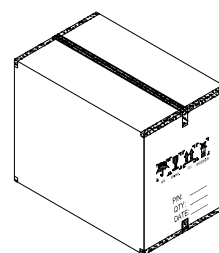
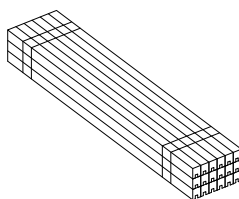


Q'ty

_____ PCS Per Tray

_____ PCS Per Carton

☐ Tube:

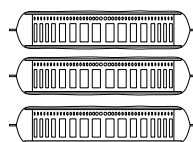
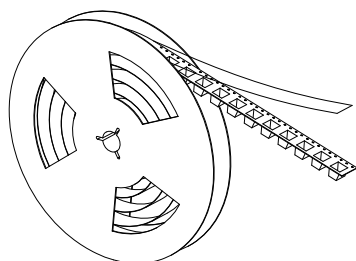


Q'ty

_____ PCS Per Tube

_____ PCS Per Carton

☒ Reel:



Vacuumize Package

Q'ty

2500 PCS Per Reel

30000 PCS Per Carton

RECOMMENDED SOLDERING PROFILE:

☒ 1. Reflow soldering profile(According to IPC/JEDEC J-STD-020C)

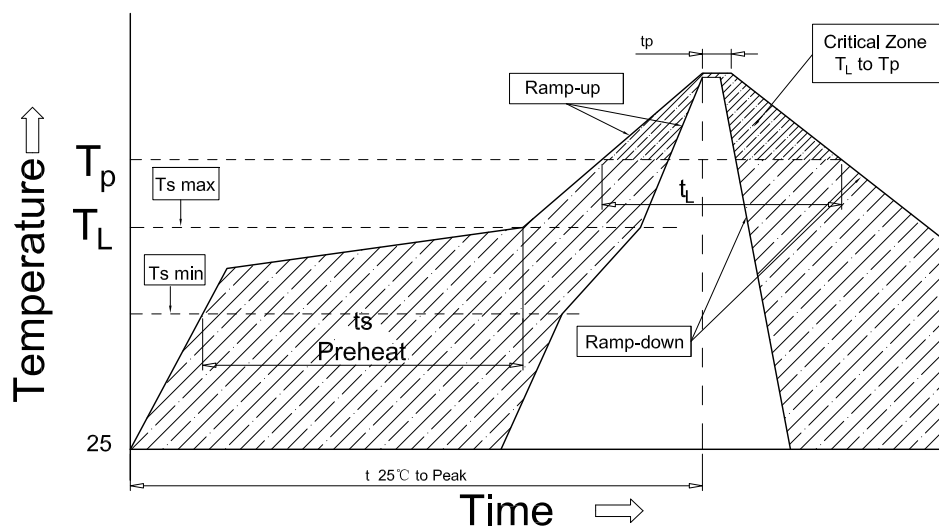


Table 1-1 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (T _{smax} to T _p)	3°C/second max	3°C/second max
Preheat		
-Temperature Min (T _{smin})	100°C	150°C
-Temperature Max (T _{smax})	150°C	200°C
-Time (t _{smin} to t _{smax})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
-Time (t _L)	60-150 seconds	60-150 seconds
Peak/Classification Temperature(T _p)	See IPC/JEDEC J-STD-020C Table 4-1	See IPC/JEDEC J-STD-020C Table 4-2
Time within 5°C of actual Peak Temperature(t _p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max	8 minutes max

Note1: All temperatures refer to topside of the package, measured on the package body surface

- Suggested soldering process: Reflow soldering
- Solder Paste: Sn96.5Ag3.0Cu0.5
- Silkscreen thickness: 0.15mm Min.

☐ 2. Wave soldering profile

